## **Linearly Graded Junction**

The Poisson equation for the case is

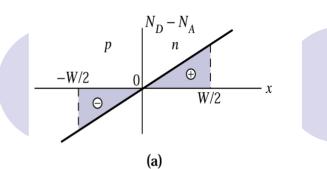
$$\frac{d^2\Psi}{dx^2} = \frac{-q}{\varepsilon_s} ax \qquad \frac{-W}{2} \le x \le \frac{W}{2}$$

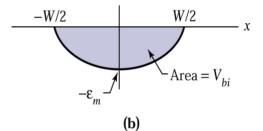
Where a is impurity gradient and W is depletion width area.

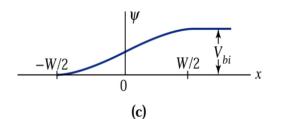
#### Figure 4-11.

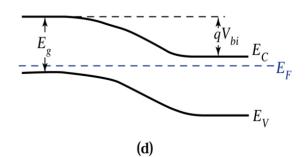
Linearly graded junction in thermal equilibrium.

- (a) Impurity distribution.
- (b) Electric-field distribution.
- (c) Potential distribution with distance.
- (d) Energy band diagram.









## Linearly graded junction

### Built in Voltage for Linearly Graded Junction

$$V_{bi} = \frac{kT}{q} \ln \left[ \frac{(a\frac{W}{2})(a\frac{W}{2})}{{n_i}^2} \right] = \frac{2kT}{q} \ln \left[ \frac{aW}{2n_i} \right]$$

# **Depletion Capacitance**

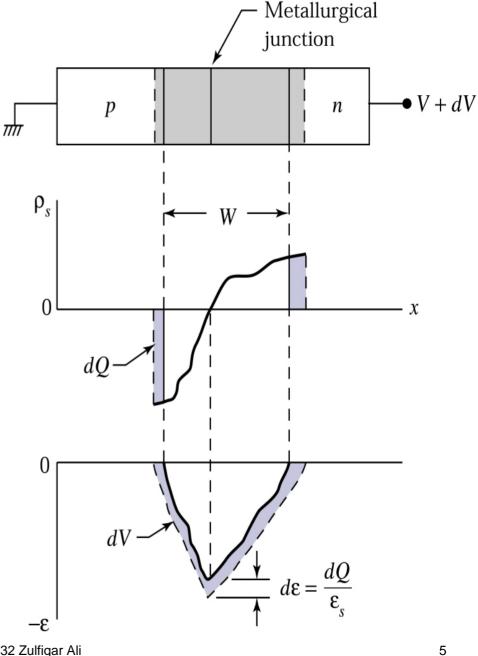
The depletion layer capacitance per unit area is defined

 $Cj = \frac{dQ}{dV}$ 

Where dQ is incremental charge per unit area as for an incremental charge per unit voltage.

#### Figure 4.13.

(a) p-n junction with an arbitrary impurity profile under reverse bias. (b) Change in space charge distribution due to change in applied bias. (c) Corresponding change in electric-field distribution.



## **Depletion Capacitance**

- Whenever voltage dv is applied. The charge filed distribution will expand. Figure shows the region bounded by dashed line.
- This increment bring increase in electric field by an amount of  $d\varepsilon = \frac{dQ}{d\xi}$

 $\mathcal{E}_{a}$ 

### Capacitance-Voltage Characteristic

- Separation between two plates represents the depletion width. Refer to the figure 13.
- For forward bias large current can flow across the junction corresponding to large number of mobile carrier.
- The incremental change of these mobile carriers with respect to the biasing voltage contributes an additional term called diffusion capacitance.

### Capacitance-Voltage Characteristic. Abrupt Junction case

$$Cj = \frac{\varepsilon s}{W} = \sqrt{\frac{q\varepsilon_s N_B}{2(V_{bi} - V)}}$$

## Varactor

- Used in many circuit applications.
- Capacitance varies with frequency.
- Concept:
- Reverse biased application depletion capacitance:

$$Cj\infty(Vbi+V_R)^{-n}$$
  
or

$$Cj\infty(V_R)^{-n}$$

## Varactor

 Voltage sensitivity with respect to capacitance is greater in abrupt junction that linear grade.

- This because of n factor which is higher in abrupt as oppose to linear grade.
- From Poisson condition establish the relationship between the depletion region and  $V_R$ .

## Varactor

 By choosing different value of m we can approximate the relationship between the voltage and junction capacitance

$$W\infty(V_R)^{\frac{1}{m+2}}$$
$$C_j = (V_R)^{\frac{-1}{m+2}}$$

 In RF circuit you can adjust the voltage to control the capacitive value therefore you can control resonant value.

## **Current Voltage Characteristic**

- A voltage applied to a p-n junction will disturb the balance diffussion and drift current.
- Forward bias voltage will increase the diffusion current and decrease the drift current.
- Reverse biased voltage will increase the drift current and reduced the diffusion current.

## Ideal characteristic.

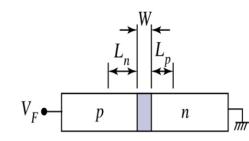
- We based on these assumptions:
- Abrupt boundaries ,outside the boundary the semiconductor assume to be neutral.
- Carrier density related by potential different.
- Low density carrier is smaller compare to higher density.
- Electron and hole are constant throughout the depletion region.

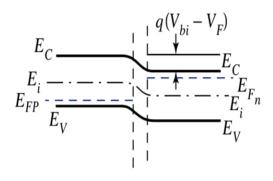
#### Figure 4-16.

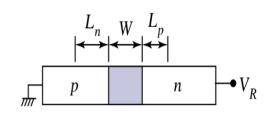
Depletion region, energy band diagram and carrier distribution.

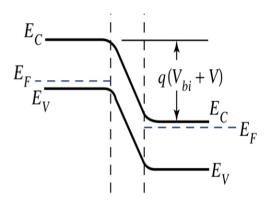
(a) Forward bias.

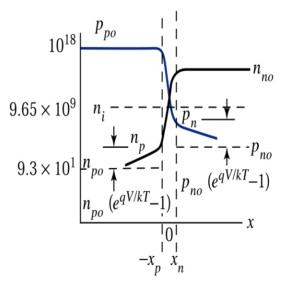
(b) Reverse bias.

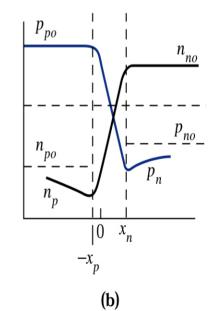




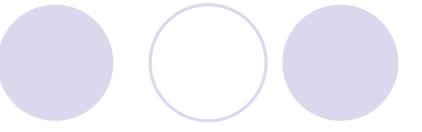








## Ideal characteristic.



### Built in Voltage

$$V_{bi} = \frac{kT}{q} \ln \frac{p_{po} n_{no}}{n_i^2}$$

### The electron density and hole density are related through the electrostatic potential different.

## Ideal Characteristic

- Forward bias cause the electrostatic potential different reduced to V<sub>bi</sub>-V<sub>F</sub>.
  Reverse bias electrostatic potential
  - increase V<sub>bi</sub>+V<sub>R</sub>

$$n_n = n_p e^{q \frac{(Vbi-V)}{kT}}$$

Where n<sub>n</sub> and n<sub>p</sub> are non-equilibrium electron densities at the boundary.

## Ideal Characteristic

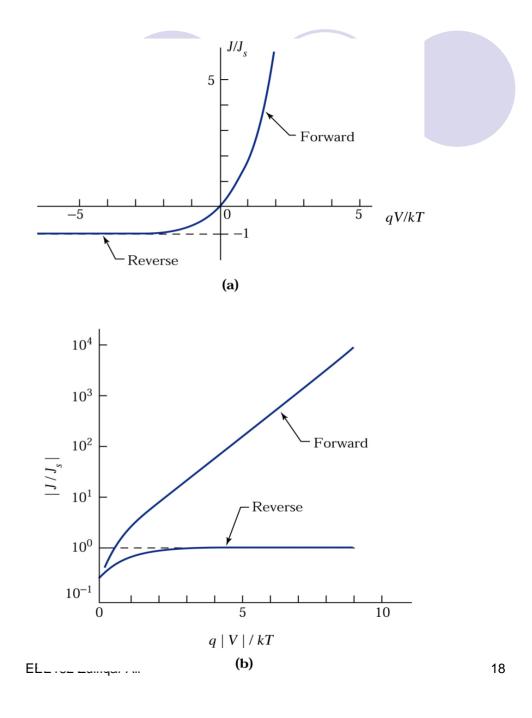
 Js saturation current Lp and Ln are diffusion length.

$$Js \equiv \frac{qD_p p_{no}}{Lp} + \frac{qD_n n_{po}}{Ln}$$

The above equation is the ideal diode equation.

#### Figure 4-18.

Ideal current-voltage characteristics. (*a*) Cartesian plot. (*b*) Semilog plot.



## **Temperature Effect**

- Temperature effect has an effect on the device performance.
- In reverse bias as well as forward bias the magnitude of diffusion and generation recombination depend strong on the temperature.

### Charge storage and transient behavior

- Under forward bias the electrons are injected into p-type and holes are injected into the n-type.
- Once injected across junction the minority carriers recombine with majority carrier and decay exponentially with distance.
- These lead to current flows and charge storage in the pn junction.

## **Minority Carrier Storage**

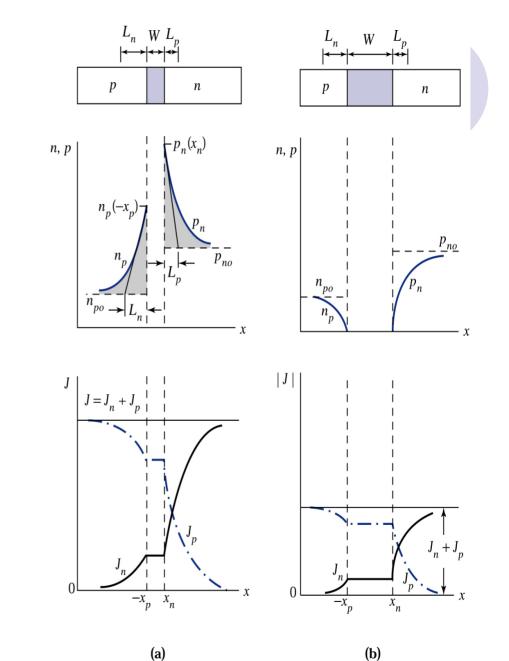
 The charge minority carrier can be found by integrating excess hole in neutral region.

$$Qp = q \int_{xn}^{\infty} (p_n - p_{no}) dx$$
$$= q L_p p_{no} (e^{\frac{qV}{kT} - 1})$$

$$Qp = \frac{Lp^2}{Dp} Jp(x_n) = \tau p Jp(x_n)$$

#### Figure 4-17.

Injected minority carrier distribution and electron and hole currents. (*a*) Forward bias. (*b*) Reverse bias. The figure illustrates idealized currents. For practical devices, the currents are not constant across the space charge layer.



## **Diffusion Capacitance**

- When the junction is forward biased the is additional significant contribution to the junction capacitance.
- This is called the diffusion capacitance denoted by C<sub>d</sub>. A is area of a device.

$$Cd = \frac{Aq^2 Lpp_{no}}{kT} e^{\frac{qV}{kT}}$$

## **Transient Behavior**

 For switching behavior the forward to reverse biased transition must be transient time short.

Under the forward biased condition the stored minority carrier

$$Qp = \tau p Jp = \tau p \frac{I_F}{A}$$
$$toff \cong \frac{QpA}{I_{Rave}} = \tau p \left(\frac{I_F}{I_{Rave}}\right)$$

## **Junction Breakdown**

- When large reverse voltage is applied to p-n junction, the junction breaks down and conducts a very large current.
- The important breakdown mechanism:
- Tunneling process and avalance mechanism.

# **Tunneling Effect**

- High electric field is applied in reverse direction valence electron make transition from valence band to conduction band.
- Only occurs if the electric field is high about 10<sup>6</sup>V/cm

## **Avalance** multiplication

- This occurs under the reverse bias condition.
- The thermally generated electron gain kinetic energy from the electric field.
- If the field is sufficiently high it can gain enough kinetic energy to break the bond creating electron hole pair.
- The newly created electron hole pair requires energy thus create more electron hole pair and this is called the avalance multiplication.